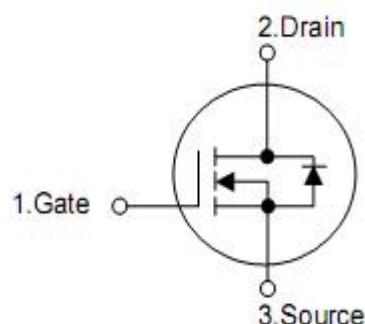
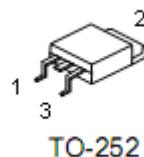


1. Features

- $R_{DS(ON)}=140\text{m}\Omega(\text{Typ.}) @ V_{GS}=10\text{V}$
- N-Channel, Logic level 5V
- Enhancement mode
- Fast Switching
- Pb-free lead plating; RoHS compliant

2. Symbol



Pin	Function
1	Gate
2	Drain
3	Source

3. Maximum ratings, at $T_J=25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Rating	Units
Drain-source breakdown voltage	V_{DSS}	100	V
Gate-source voltage $T_C=25^\circ\text{C}$	V_{GS}	± 20	V
Diode continuous forward current	I_S	9	A
Continuous drain current , $V_{GS}@10\text{V}$	I_D	9	A
$T_A=100^\circ\text{C}$		5.8	
Pulsed drain current tested ¹ $T_C=25^\circ\text{C}$	I_{DM}	36	
Maximum power dissipation	P_D	45	W
Avalanche energy , single pulsed ² $L=0.5\text{mH}$	E_{AS}	20.25	mJ
Storage and operating temperature range	$T_{STG} T_J$	-55 to 150	°C

4. Thermal characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal resistance junction-case	$R_{\theta JC}$	-	2.78	°C/W
Thermal resistance junction-ambient	$R_{\theta JA}$	-	62.5	

5. Ordering information

Part number	Package
KND4810A	TO-252

6. Electrical characteristics

($T_C=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100	-	-	V
Drain-source on-resistance ³	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=6\text{A}$	-	140m	160m	Ω
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=5\text{A}$	-	150m	180m	
Gate threshold voltage	$V_{\text{GS}(\text{TH})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.8	3.0	V
Zero gate voltage Drain Current	I_{DSS}	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$ $T_C=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$ $T_C=125^\circ\text{C}$	-	-	100	
Gate-source forward leakage	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Total gate charge	Q_g	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=10\text{A}$ $V_{\text{GS}}=10\text{V}$	-	14	-	nC
Gate-source charge	Q_{gs}		-	3.5	-	
Gate-drain charge	Q_{gd}		-	1.8	-	
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=50\text{V}, I_{\text{D}}=10\text{A},$ $R_G=10\Omega, V_{\text{GS}}=10\text{V}$	-	12.6	-	ns
Rise time	t_r		-	4.2	-	
Turn-off delay time	$t_{\text{d}(\text{off})}$		-	32	-	
Fall time	t_f		-	4.6	-	
Input capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}$ $f=1\text{MHz}$	-	950	-	pF
Output capacitance	C_{oss}		-	43	-	
Reverse transfer capacitance	C_{rss}		-	22	-	
Diode forward voltage	V_{SD}	$I_{\text{SD}}=2\text{A}, V_{\text{GS}}=0\text{V}$	-	0.71	1.3	V
Max.diode forward current	I_s		-	-	10	A

Note:

1. Repetitive rating; pulse width limited by max. junction temperature.
2. Limited by T_{JMAX} , starting $T_J=25^\circ\text{C}$, $L=0.5\text{mH}$, $R_G=25\Omega$, $I_{\text{AS}}=9\text{A}$, $V_{\text{GS}}=10\text{V}$, Part not recommended for use above this value.
3. Pulse width $\leq 300\text{us}$; duty cycle $\leq 2\%$

7. Typical operating characteristics

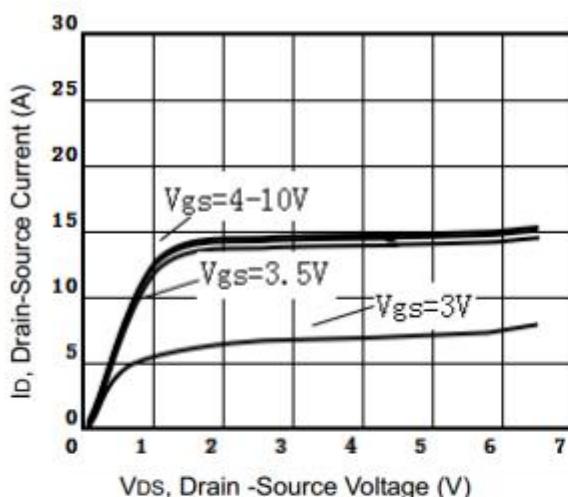


Fig1. Typical Output Characteristics

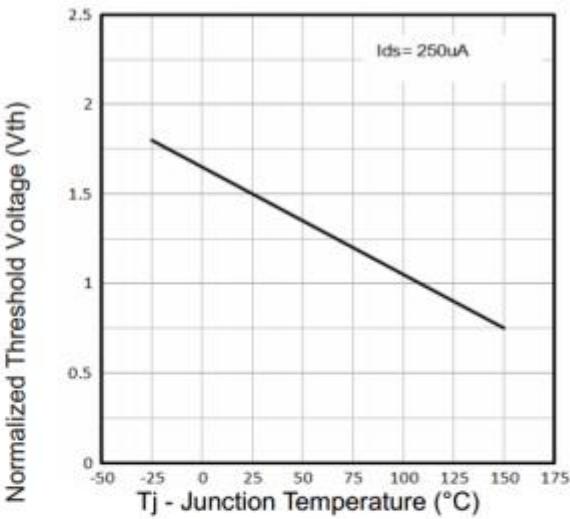


Fig2. Normalized Threshold Voltage Vs. Temperature

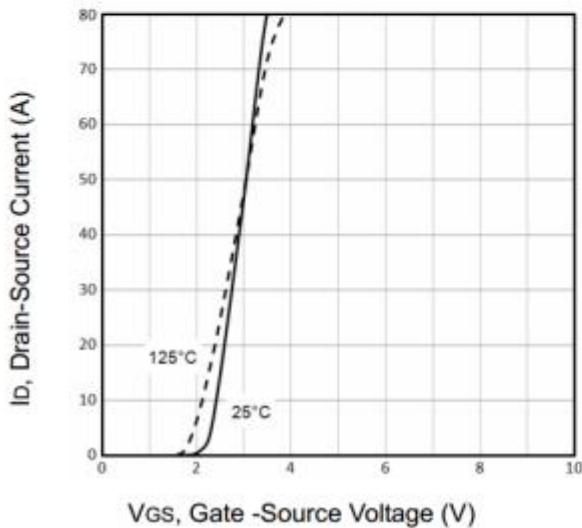


Fig3. Typical Transfer Characteristics

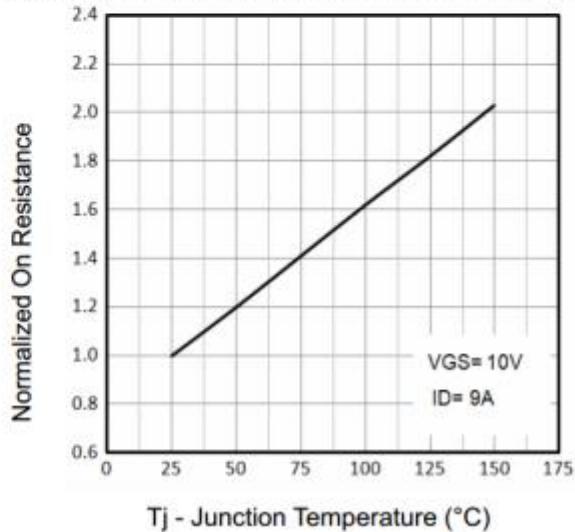


Fig4. Normalized On-Resistance Vs. Temperature

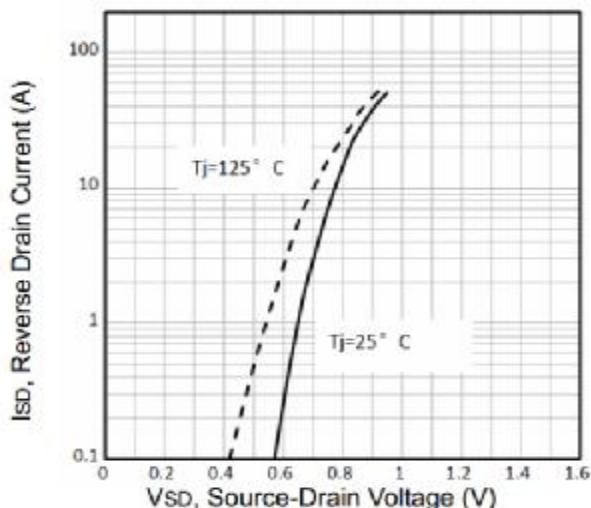


Fig5. Typical Source-Drain Diode Forward Voltage

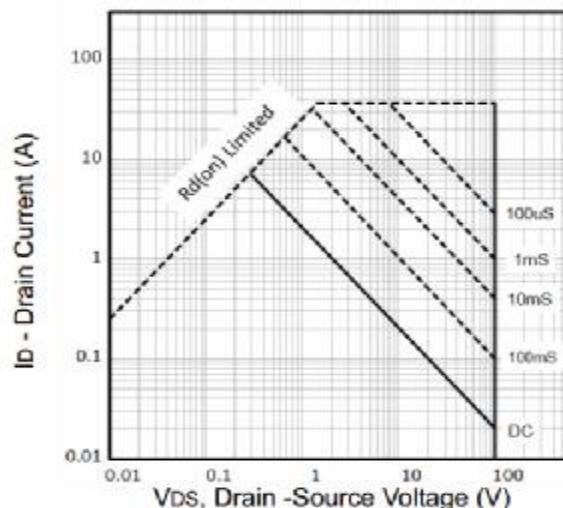


Fig6. Maximum Safe Operating Area

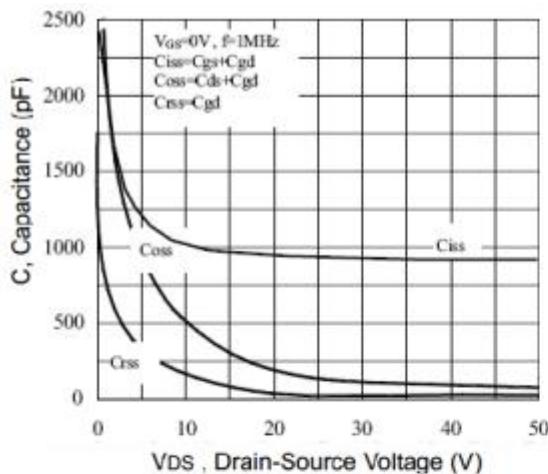


Fig7. Typical Capacitance Vs.Drain-Source Voltage

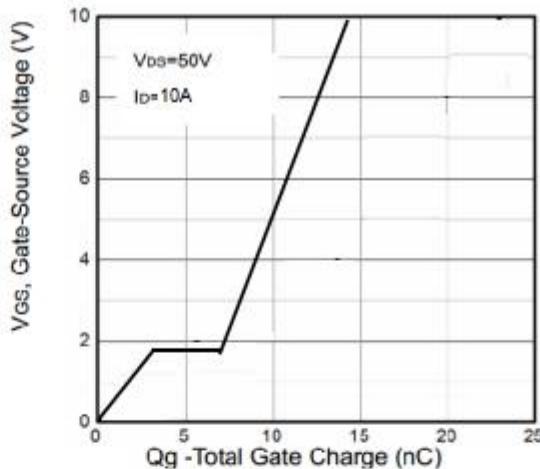


Fig8. Typical Gate Charge Vs.Gate-Source

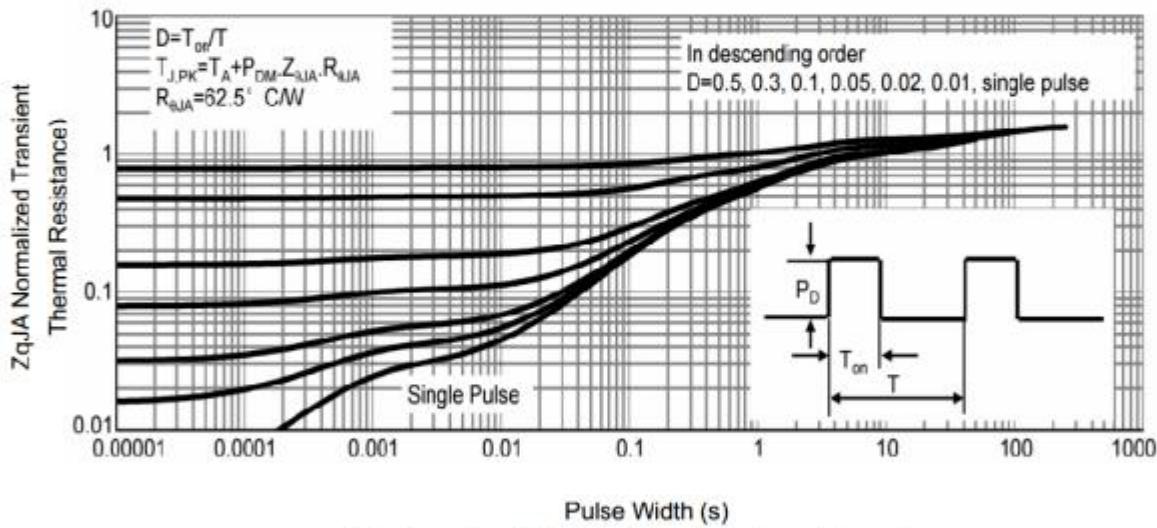


Fig9. Normalized Maximum Transient Thermal Impedance



Fig10. Unclamped Inductive Test Circuit and waveforms

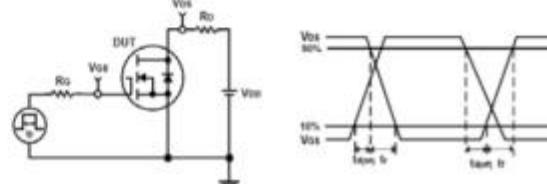


Fig11. Switching Time Test Circuit and waveforms